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**For Immediate Release**

**Deca Technologies Introduces Chris Seams as New CEO**

*Brings Operational, Manufacturing, and Sales and Marketing Management Experience  
To Lead Growth in Wafer Level Packaging Market*

TEMPE, AZ., June 24, 2013 – Deca Technologies, an electronic interconnect solutions provider to the semiconductor industry, today announced it has named semiconductor industry veteran Chris Seams its new CEO. Seams brings more than 25 years expertise in managing operations, manufacturing, and sales and marketing. He has also been appointed to the Company's board of directors.

Seams joins Deca from Cypress Semiconductor Corporation, where he served as executive vice president of Sales and Marketing. He takes over for Tim Olson, who will now serve as Deca's Chief Technology Officer and a member of its board of directors.

"Deca has two key value propositions: truly revolutionary wafer level packaging technology and industry-leading manufacturing efficiency," said T.J. Rodgers, chairman of Deca's board of directors. "Chris brings a wealth of manufacturing experience to the position. He directly managed Cypress's manufacturing for 14 years, building up its reputation for world-class efficiency. We are confident Chris will successfully build upon Deca's strong inroads with top customers and lay the groundwork for the next level of the company's growth."

"This is an exciting time to be joining Deca," said Seams. "The company is poised for rapid growth with the continued development of its offerings. I welcome the opportunity to lead Deca's efforts to bring the potential of our wafer scale packaging capabilities to reality. In so doing, we will transform the way our customers—the leading semiconductor manufacturers around the world—approach wafer level packaging."

Seams joined Cypress in 1990, where other assignments included technical and operational management in manufacturing, development, and operations. Prior to joining Cypress, he

worked in process development for Advanced Micro Devices and Philips Research Laboratories.

Seams is a senior member of IEEE, serves on the Engineering Advisory Council for Texas A&M University, and is on the board of directors of Tessera Technologies, Inc. Seams earned his bachelor's degree in electrical engineering from Texas A&M University and his master's degree in electrical and computer engineering from the University of Texas at Austin.

### **About Deca Technologies Inc**

Founded in 2009 and launched in November 2011, Deca Technologies is an electronic interconnect solutions provider offering wafer level packaging (WLP) services to the semiconductor industry. Headquartered in Tempe, AZ and with global capabilities, Deca is a majority-owned and fully independent subsidiary of Cypress Semiconductor Corp. (NASDAQ: CY). Deca's mission is to deliver an exceptional customer experience through its proprietary and transformative interconnect technology.

Integrating its solar and semiconductor background, Deca leverages unique equipment, processes and operational methods to break down traditional barriers in the continued adoption and growth of next generation wafer level electronic interconnect.

For more information, please visit [www.decatechnologies.com](http://www.decatechnologies.com).

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